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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

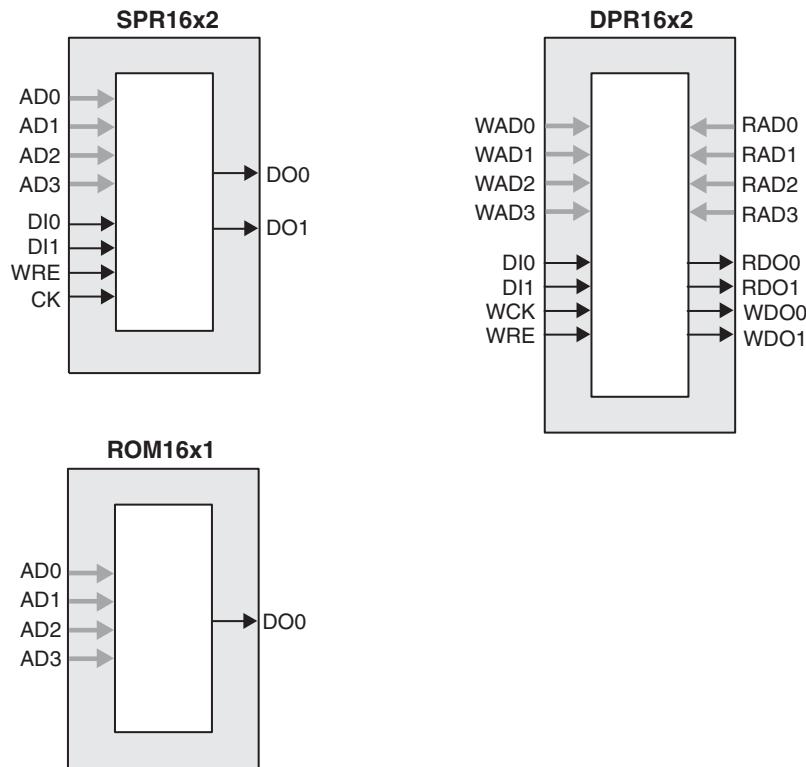
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	101
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	132-LFBGA, CSPBGA
Supplier Device Package	132-CSPBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200c-5mn132c

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

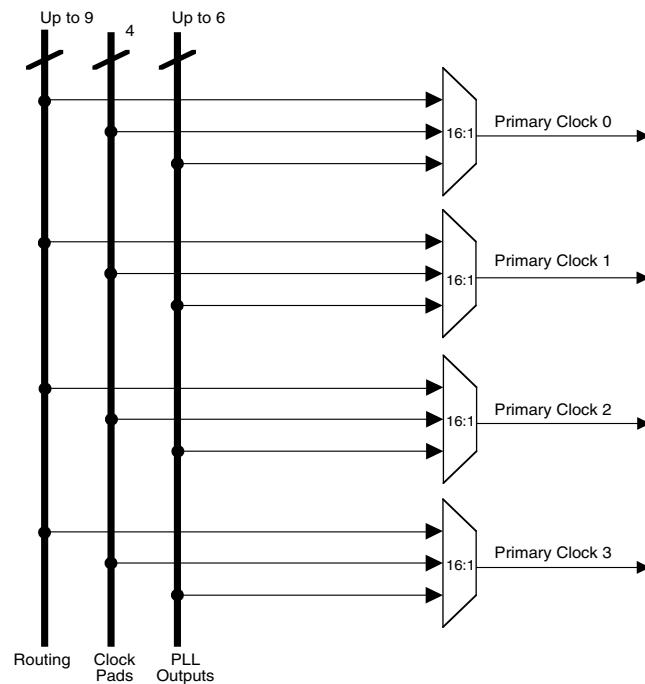
Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Figure 2-8. Primary Clocks for MachXO1200 and MachXO2280 Devices



Four secondary clocks are generated from four 16:1 muxes as shown in Figure 2-9. Four of the secondary clock sources come from dual function clock pins and 12 come from internal routing.

Figure 2-9. Secondary Clocks for MachXO Devices

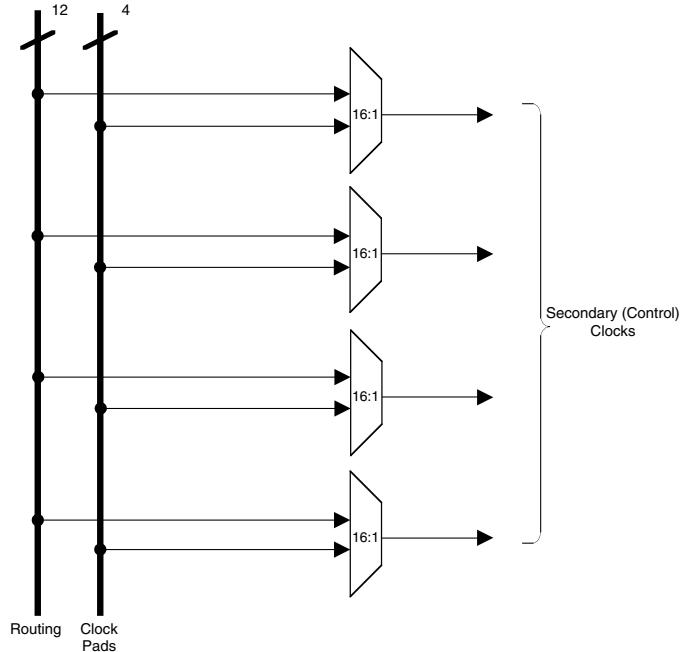


Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from PLL output, clock net, routing/external pin or internal feedback from CLKINTFB port
RST	I	"1" to reset the input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
CLKINTFB	O	Internal feedback source, CLKOP divider output before CLOCKTREE
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

sysMEM Memory

The MachXO1200 and MachXO2280 devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

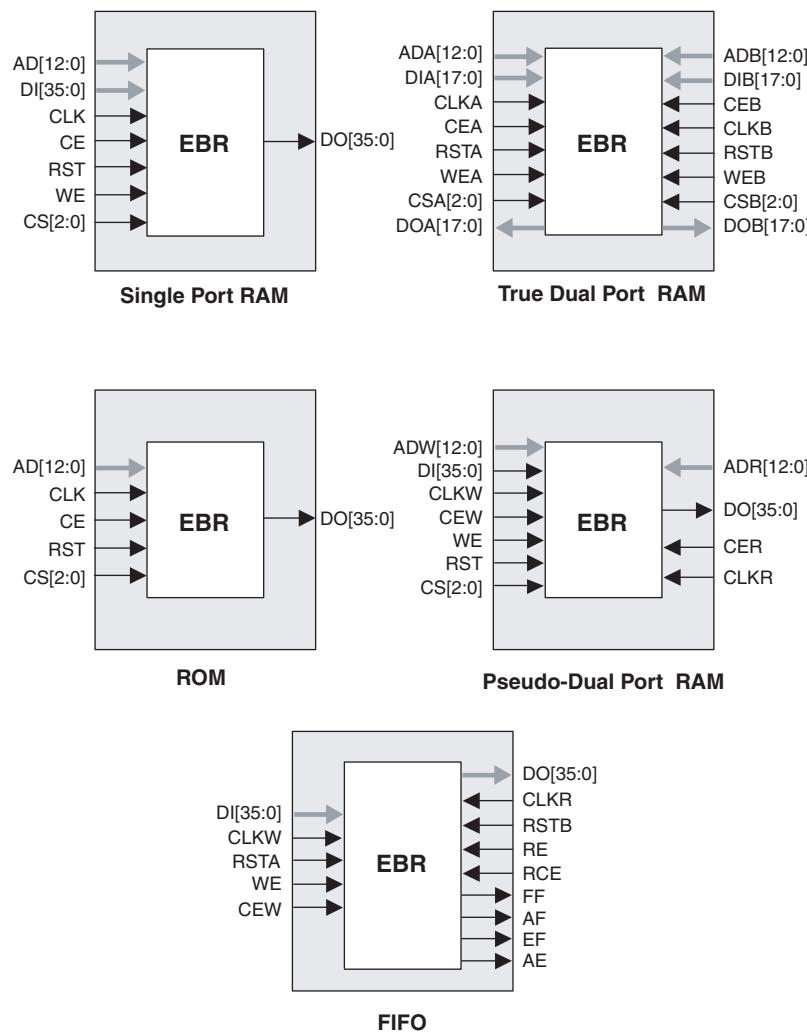
Memory Cascading

Larger and deeper blocks of RAMs can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual, Pseudo-Dual Port and FIFO Modes

Figure 2-12 shows the five basic memory configurations and their input/output names. In all the sysMEM RAM modes, the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the memory array output.

Figure 2-12. sysMEM Memory Primitives



of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC} , V_{CCAUX} , and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. Left and Right sysIO Buffer Pairs

The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to V_{CCIO} . The I/O pins will maintain the blank configuration until V_{CC} , V_{CCAUX} and V_{CCIO} have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Initialization Supply Current^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I _{CC}	Core Power Supply	LCMxo256C	13	mA
		LCMxo640C	17	mA
		LCMxo1200C	21	mA
		LCMxo2280C	23	mA
		LCMxo256E	10	mA
		LCMxo640E	14	mA
		LCMxo1200E	18	mA
		LCMxo2280E	20	mA
I _{CCAUX}	Auxiliary Power Supply V _{CCAUX} = 3.3V	LCMxo256C/E	10	mA
		LCMxo640E/C	13	mA
		LCMxo1200E/C	24	mA
		LCMxo2280E/C	25	mA
I _{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Frequency = 0MHz.
4. Typical user pattern.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank, V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current^{1, 2, 3, 4}

Symbol	Parameter	Device	Typ. ⁵	Units
I _{CC}	Core Power Supply	LCMxo256C	9	mA
		LCMxo640C	11	mA
		LCMxo1200C	16	mA
		LCMxo2280C	22	mA
		LCMxo256E	6	mA
		LCMxo640E	8	mA
		LCMxo1200E	12	mA
		LCMxo2280E	14	mA
I _{CCAUX}	Auxiliary Power Supply V _{CCAUX} = 3.3V	LCMxo256C/E	8	mA
		LCMxo640C/E	10	mA
		LCMxo1200/E	15	mA
		LCMxo2280C/E	16	mA
I _{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Typical user pattern.
4. JTAG programming is at 25MHz.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

sysIO Differential Electrical Characteristics

LVDS

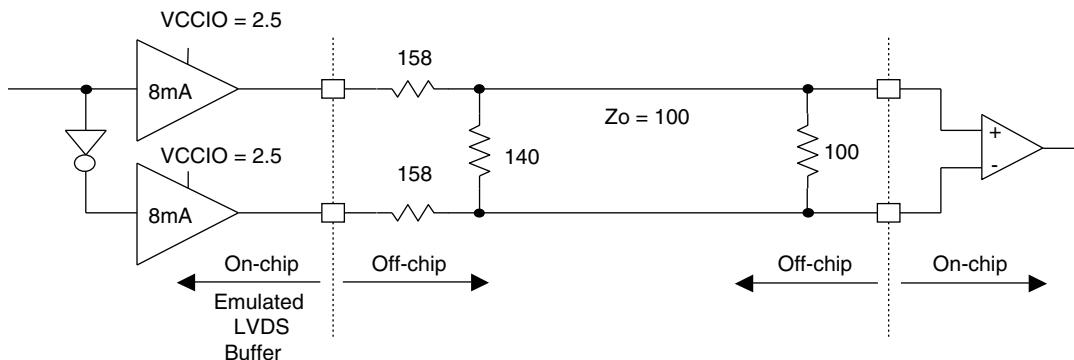
Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	$100\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		$200\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		$350\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on	—	—	+/-10	μA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100 \text{ Ohm}$	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} - V_{OM})/2, R_T = 100 \text{ Ohm}$	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	$V_{OD} = 0\text{V}$ Driver outputs shorted	—	—	6	mA

LVDS Emulation

MachXO devices can support LVDS outputs via emulation (LVDS25E), in addition to the LVDS support that is available on-chip on certain devices. The output is emulated using complementary LVCMS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

Figure 3-1. LVDS Using External Resistors (LVDS25E)



Note: All resistors are $\pm 1\%$.

The LVDS differential input buffers are available on certain devices in the MachXO family.

Table 3-1. LVDS DC Conditions
Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ω
R_S	Driver series resistor	294	Ω
R_P	Driver parallel resistor	121	Ω
R_T	Receiver termination	100	Ω
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	Ω
I_{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

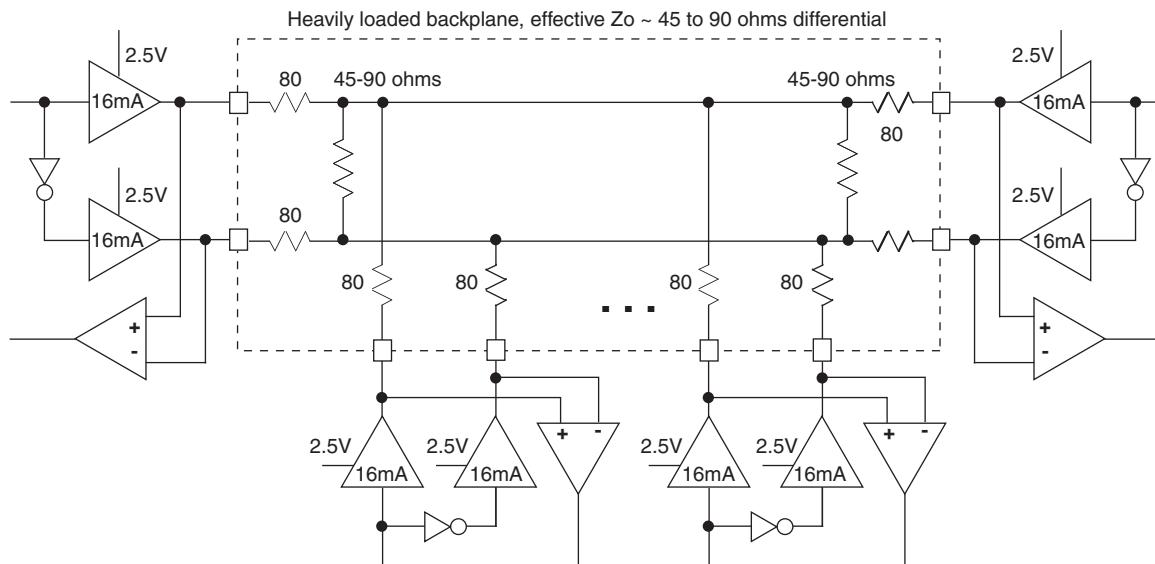
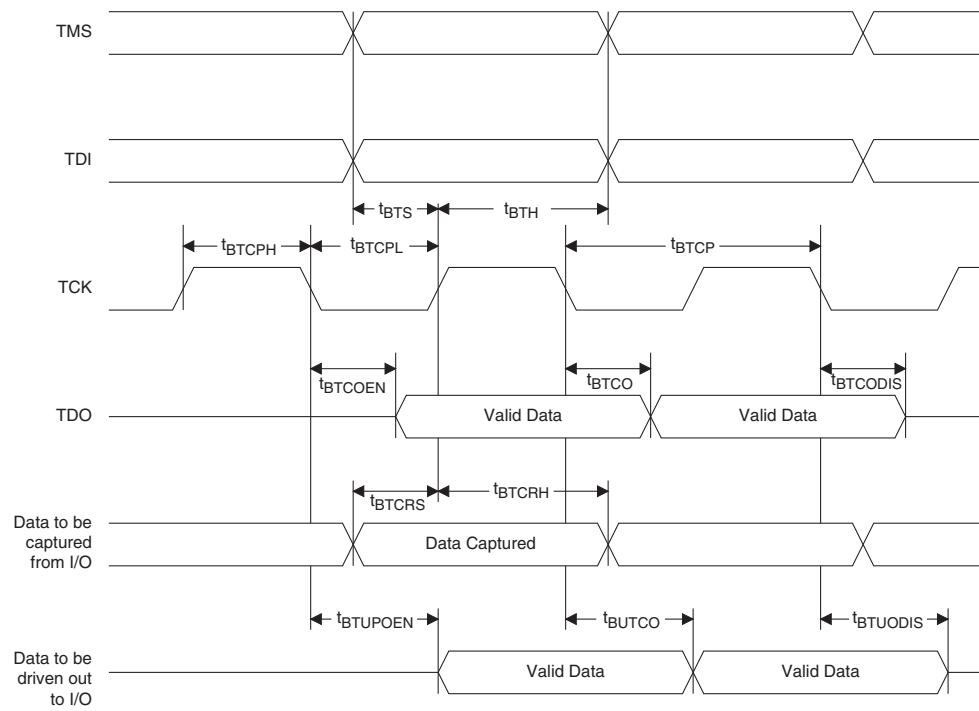
Figure 3-2. BLVDS Multi-point Output Example


Figure 3-5. JTAG Port Timing Waveforms



Power Supply and NC

Signal	100 TQFP ¹	144 TQFP ¹	100 csBGA ²
VCC	LCMxo256/640: 35, 90 LCMxo1200/2280: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	LCMxo256: 60, 74, 92 LCMxo640: 80, 92 LCMxo1200/2280: 94	LCMxo640: 117, 135 LCMxo1200/2280: 135	LCMxo256: H14, A14, B5 LCMxo640: B12, B5
VCCIO1	LCMxo256: 10, 24, 41 LCMxo640: 60, 74 LCMxo1200/2280: 80	LCMxo640: 82, 98 LCMxo1200/2280: 117	LCMxo256: G1, P1, P10 LCMxo640: H14, A14
VCCIO2	LCMxo256: None LCMxo640: 29, 41 LCMxo1200/2280: 70	LCMxo640: 38, 63 LCMxo1200/2280: 98	LCMxo256: None LCMxo640: P4, P10
VCCIO3	LCMxo256: None LCMxo640: 10, 24 LCMxo1200/2280: 56	LCMxo640: 10, 26 LCMxo1200/2280: 82	LCMxo256: None LCMxo640: G1, P1
VCCIO4	LCMxo256/640: None LCMxo1200/2280: 44	LCMxo640: None LCMxo1200/2280: 63	—
VCCIO5	LCMxo256/640: None LCMxo1200/2280: 27	LCMxo640: None LCMxo1200/2280: 38	—
VCCIO6	LCMxo256/640: None LCMxo1200/2280: 20	LCMxo640: None LCMxo1200/2280: 26	—
VCCIO7	LCMxo256/640: None LCMxo1200/2280: 6	LCMxo640: None LCMxo1200/2280: 10	—
VCCAUX	LCMxo256/640: 88 LCMxo1200/2280: 36, 90	53, 128	B7
GND ³	LCMxo256: 40, 84, 62, 75, 93, 12, 25, 42 LCMxo640: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 LCMxo1200/2280: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	LCMxo256: N9, B9, G14, B13, A4, H1, N2, N10 LCMxo640: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC ⁴			—

1. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
2. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
3. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
4. NC pins should not be connected to any active signals, VCC or GND.

LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA (Cont.)

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
P13	PB5A	1			P13	PB9C	2		T
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN	
P14	PB5C	1		T	P14	PB9D	2		C
N13	PB5D	1		C	N13	PB9F	2		
N14	PR9B	0		C	N14	PR11D	1		C
M14	PR9A	0		T	M14	PR11B	1		C
L13	PR8B	0		C	L13	PR11C	1		T
L14	PR8A	0		T	L14	PR11A	1		T
M13	PR7D	0		C	M13	PR10D	1		C
K14	PR7C	0		T	K14	PR10C	1		T
K13	PR7B	0		C	K13	PR10B	1		C
J14	PR7A	0		T	J14	PR10A	1		T
J13	PR6B	0		C	J13	PR9D	1		
H13	PR6A	0		T	H13	PR9B	1		
G14	GNDIO0	0			G14	GNDIO1	1		
G13	PR5D	0		C	G13	PR7B	1		
F14	PR5C	0		T	F14	PR6C	1		
F13	PR5B	0		C	F13	PR6B	1		
E14	PR5A	0		T	E14	PR5D	1		
E13	PR4B	0		C	E13	PR5B	1		
D14	PR4A	0		T	D14	PR4D	1		
D13	PR3D	0		C	D13	PR4B	1		
C14	PR3C	0		T	C14	PR3D	1		
C13	PR3B	0		C	C13	PR3B	1		
B14	PR3A	0		T	B14	PR2D	1		
C12	PR2B	0		C	C12	PR2B	1		
B13	GNDIO0	0			B13	GNDIO1	1		
A13	PR2A	0		T	A13	PT9F	0		C
A12	PT5C	0			A12	PT9E	0		T
B11	PT5B	0		C	B11	PT9C	0		
A11	PT5A	0		T	A11	PT9A	0		
B12	PT4F	0		C	B12	VCCIO0	0		
A10	PT4E	0		T	A10	GNDIO0	0		
B10	PT4D	0		C	B10	PT7E	0		
A9	PT4C	0		T	A9	PT7A	0		
A8	PT4B	0	PCLK0_1**	C	A8	PT6B	0	PCLK0_1**	
B8	PT4A	0	PCLK0_0**	T	B8	PT5B	0	PCLK0_0**	C
A7	PT3D	0		C	A7	PT5A	0		T
B7	VCCAUX	-			B7	VCCAUX	-		
A6	PT3C	0		T	A6	PT4F	0		
B6	VCC	-			B6	VCC	-		
A5	PT3B	0		C	A5	PT3F	0		

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
132 csBGA**

LCMxo640					LCMxo1200					LCMxo2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B1	PL2A	3		T	B1	PL2A	7		T	B1	PL2A	7	LUM0_PLLT_FB_A	T
C1	PL2B	3		C	C1	PL3C	7		T	C1	PL3C	7	LUM0_PLLT_IN_A	T
B2	PL2C	3		T	B2	PL2B	7		C	B2	PL2B	7	LUM0_PLLC_FB_A	C
C2	PL2D	3		C	C2	PL4A	7		T*	C2	PL4A	7		T*
C3	PL3A	3		T	C3	PL3D	7		C	C3	PL3D	7	LUM0_PLLC_IN_A	C
D1	PL3B	3		C	D1	PL4B	7		C*	D1	PL4B	7		C*
D3	PL3D	3			D3	PL4C	7			D3	PL4C	7		
E1	GNDIO3	3			E1	GNDIO7	7			E1	GNDIO7	7		
E2	PL5A	3		T	E2	PL6A	7		T*	E2	PL7A	7		T*
E3	PL5B	3	GSRN	C	E3	PL6B	7	GSRN	C*	E3	PL7B	7	GSRN	C*
F2	PL5D	3			F2	PL6D	7			F2	PL7D	7		
F3	PL6B	3			F3	PL7C	7		T	F3	PL9C	7		T
G1	PL6C	3		T	G1	PL7D	7		C	G1	PL9D	7		C
G2	PL6D	3		C	G2	PL8C	7		T	G2	PL10C	7		T
G3	PL7A	3		T	G3	PL8D	7		C	G3	PL10D	7		C
H2	PL7B	3		C	H2	PL10A	6		T*	H2	PL12A	6		T*
H1	PL7C	3			H1	PL10B	6		C*	H1	PL12B	6		C*
H3	VCC	-			H3	VCC	-			H3	VCC	-		
J1	PL8A	3			J1	PL11B	6			J1	PL14D	6		C
J2	PL8C	3	TSALL		J2	PL11C	6	TSALL	T	J2	PL14C	6	TSALL	T
J3	PL9A	3		T	J3	PL11D	6		C	J3	PL14B	6		
K2	PL9B	3		C	K2	PL12A	6		T*	K2	PL15A	6		T*
K1	PL9C	3			K1	PL12B	6		C*	K1	PL15B	6		C*
L2	GNDIO3	3			L2	GNDIO6	6			L2	GNDIO6	6		
L1	PL10A	3		T	L1	PL14A	6	LLM0_PLLT_FB_A	T*	L1	PL17A	6	LLM0_PLLT_FB_A	T*
L3	PL10B	3		C	L3	PL14B	6	LLM0_PLLC_FB_A	C*	L3	PL17B	6	LLM0_PLLC_FB_A	C*
M1	PL11A	3		T	M1	PL15A	6	LLM0_PLLT_IN_A	T*	M1	PL18A	6	LLM0_PLLT_IN_A	T*
N1	PL11B	3		C	N1	PL16A	6		T	N1	PL19A	6		T
M2	PL11C	3		T	M2	PL15B	6	LLM0_PLLC_IN_A	C*	M2	PL18B	6	LLM0_PLLC_IN_A	C*
P1	PL11D	3		C	P1	PL16B	6		C	P1	PL19B	6		C
P2	GNDIO2	2			P2	GNDIO5	5			P2	GNDIO5	5		
P3	TMS	2	TMS		P3	TMS	5	TMS		P3	TMS	5	TMS	
M3	PB2C	2		T	M3	PB2C	5		T	M3	PB2A	5		T
N3	PB2D	2		C	N3	PB2D	5		C	N3	PB2B	5		C
P4	TCK	2	TCK		P4	TCK	5	TCK		P4	TCK	5	TCK	
M4	PB3B	2			M4	PB3B	5			M4	PB3B	5		
N4	PB3C	2		T	N4	PB4A	5		T	N4	PB4A	5		T
P5	PB3D	2		C	P5	PB4B	5		C	P5	PB4B	5		C
N5	TDO	2	TDO		N5	TDO	5	TDO		N5	TDO	5	TDO	
M5	TDI	2	TDI		M5	TDI	5	TDI		M5	TDI	5	TDI	
N6	PB4E	2		T	N6	PB5C	5			N6	PB6C	5		
P6	VCC	-			P6	VCC	-			P6	VCC	-		
M6	PB4F	2		C	M6	PB6A	5			M6	PB8A	5		
P7	VCCAUX	-			P7	VCCAUX	-			P7	VCCAUX	-		
N7	PB5A	2		T	N7	PB6F	5			N7	PB8F	5		
M7	PB5B	2	PCLK2_1***	C	M7	PB7B	4	PCLK4_1***		M7	PB10F	4	PCLK4_1***	
N8	PB5D	2			N8	PB7C	4		T	N8	PB10C	4		T
P8	PB6A	2		T	P8	PB7D	4		C	P8	PB10D	4		C
M8	PB6B	2	PCLK2_0***	C	M8	PB7F	4	PCLK4_0***		M8	PB10B	4	PCLK4_0***	
N9	PB7A	2		T	N9	PB9A	4		T	N9	PB12A	4		T

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 144 TQFP (Cont.)**

Pin Number	LCMxo640				LCMxo1200				LCMxo2280				
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	
101	PR3D	1		C	PR4B	2			C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2			T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2			C	PR4D	2		C
104	PR2D	1		C	PR3C	2			T	PR4C	2		T
105	PR3A	1		T	PR3B	2			C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2			T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2			C	PR3B	2		C*
108	PR2A	1		T	PR2A	2			T	PR3A	2		T*
109	PT9F	0		C	PT11D	1			C	PT16D	1		C
110	PT9D	0		C	PT11C	1			T	PT16C	1		T
111	PT9E	0		T	PT11B	1			C	PT16B	1		C
112	PT9B	0		C	PT11A	1			T	PT16A	1		T
113	PT9C	0		T	PT10F	1			C	PT15D	1		C
114	PT9A	0		T	PT10E	1			T	PT15C	1		T
115	PT8C	0			PT10D	1			C	PT14B	1		C
116	PT8B	0		C	PT10C	1			T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1				VCCIO1	1		
118	GNDIO0	0			GNDIO1	1				GNDIO1	1		
119	PT8A	0		T	PT9F	1			C	PT12F	1		C
120	PT7E	0			PT9E	1			T	PT12E	1		T
121	PT7C	0			PT9B	1			C	PT12D	1		C
122	PT7A	0			PT9A	1			T	PT12C	1		T
123	GND	-			GND	-				GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***			PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1			C	PT9D	1		C
126	PT5C	0			PT7A	1			T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***			PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-				VCCAUX	-		
129	VCC	-			VCC	-				VCC	-		
130	PT4D	0			PT5D	0			C	PT7B	0		C
131	PT4B	0		C	PT5C	0			T	PT7A	0		T
132	PT4A	0		T	PT5B	0			C	PT6D	0		
133	PT3F	0			PT5A	0			T	PT6E	0		T
134	PT3D	0			PT4B	0				PT6F	0		C
135	VCCIO0	0			VCCIO0	0				VCCIO0	0		
136	GNDIO0	0			GNDIO0	0				GNDIO0	0		
137	PT3B	0		C	PT3D	0			C	PT4B	0		T
138	PT2F	0		C	PT3C	0			T	PT4A	0		C
139	PT3A	0		T	PT3B	0			C	PT3B	0		C
140	PT2D	0		C	PT3A	0			T	PT3A	0		T
141	PT2E	0		T	PT2D	0			C	PT2D	0		C
142	PT2B	0		C	PT2C	0			T	PT2C	0		T
143	PT2C	0		T	PT2B	0			C	PT2B	0		C
144	PT2A	0		T	PT2A	0			T	PT2A	0		T

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs are single-ended.

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
E13	PT16D	1		C
C15	PT16C	1		T
F13	PT16B	1		C
D14	PT16A	1		T
A18	PT15D	1		C
B17	PT15C	1		T
A16	PT15B	1		C
A17	PT15A	1		T
VCC	VCC	-		
D13	PT14D	1		C
F12	PT14C	1		T
C14	PT14B	1		C
E12	PT14A	1		T
C13	PT13D	1		C
B16	PT13C	1		T
B15	PT13B	1		C
A15	PT13A	1		T
VCCIO1	VCCIO1	1		
GND	GNDIO1	1		
B14	PT12F	1		C
A14	PT12E	1		T
D12	PT12D	1		C
F11	PT12C	1		T
B13	PT12B	1		C
A13	PT12A	1		T
C12	PT11D	1		C
GND	GND	-		
B12	PT11C	1		T
E11	PT11B	1		C
D11	PT11A	1		T
C11	PT10F	1		C
A12	PT10E	1		T
VCCIO1	VCCIO1	1		
GND	GNDIO1	1		
F10	PT10D	1		C
D10	PT10C	1		T
B11	PT10B	1	PCLK1_1***	C
A11	PT10A	1		T
E10	PT9D	1		C
C10	PT9C	1		T
D9	PT9B	1	PCLK1_0***	C
E9	PT9A	1		T
B10	PT8F	0		C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3T100C	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMxo2280C-4T100C	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMxo2280C-5T100C	2280	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMxo2280C-3T144C	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMxo2280C-4T144C	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMxo2280C-5T144C	2280	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMxo2280C-3M132C	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMxo2280C-4M132C	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMxo2280C-5M132C	2280	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMxo2280C-3B256C	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMxo2280C-4B256C	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMxo2280C-5B256C	2280	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMxo2280C-3FT256C	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMxo2280C-4FT256C	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMxo2280C-5FT256C	2280	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM
LCMxo2280C-3FT324C	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	COM
LCMxo2280C-4FT324C	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	COM
LCMxo2280C-5FT324C	2280	1.8V/2.5V/3.3V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3T100C	256	1.2V	78	-3	TQFP	100	COM
LCMxo256E-4T100C	256	1.2V	78	-4	TQFP	100	COM
LCMxo256E-5T100C	256	1.2V	78	-5	TQFP	100	COM
LCMxo256E-3M100C	256	1.2V	78	-3	csBGA	100	COM
LCMxo256E-4M100C	256	1.2V	78	-4	csBGA	100	COM
LCMxo256E-5M100C	256	1.2V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3T100C	640	1.2V	74	-3	TQFP	100	COM
LCMxo640E-4T100C	640	1.2V	74	-4	TQFP	100	COM
LCMxo640E-5T100C	640	1.2V	74	-5	TQFP	100	COM
LCMxo640E-3M100C	640	1.2V	74	-3	csBGA	100	COM
LCMxo640E-4M100C	640	1.2V	74	-4	csBGA	100	COM
LCMxo640E-5M100C	640	1.2V	74	-5	csBGA	100	COM
LCMxo640E-3T144C	640	1.2V	113	-3	TQFP	144	COM
LCMxo640E-4T144C	640	1.2V	113	-4	TQFP	144	COM
LCMxo640E-5T144C	640	1.2V	113	-5	TQFP	144	COM
LCMxo640E-3M132C	640	1.2V	101	-3	csBGA	132	COM
LCMxo640E-4M132C	640	1.2V	101	-4	csBGA	132	COM
LCMxo640E-5M132C	640	1.2V	101	-5	csBGA	132	COM
LCMxo640E-3B256C	640	1.2V	159	-3	caBGA	256	COM
LCMxo640E-4B256C	640	1.2V	159	-4	caBGA	256	COM
LCMxo640E-5B256C	640	1.2V	159	-5	caBGA	256	COM
LCMxo640E-3FT256C	640	1.2V	159	-3	ftBGA	256	COM
LCMxo640E-4FT256C	640	1.2V	159	-4	ftBGA	256	COM
LCMxo640E-5FT256C	640	1.2V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMxo256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMxo256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMxo256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMxo640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMxo640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMxo640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMxo640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMxo640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMxo640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMxo640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMxo640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMxo640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMxo640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMxo640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMxo1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMxo1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMxo1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMxo1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMxo1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMxo1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMxo1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMxo1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMxo1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMxo2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMxo2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMxo2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMxo2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMxo2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMxo2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMxo2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMxo2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMxo2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMxo2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMxo2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3TN100C	1200	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMxo1200E-4TN100C	1200	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMxo1200E-5TN100C	1200	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMxo1200E-3TN144C	1200	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMxo1200E-4TN144C	1200	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMxo1200E-5TN144C	1200	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMxo1200E-3MN132C	1200	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMxo1200E-4MN132C	1200	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMxo1200E-5MN132C	1200	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMxo1200E-3BN256C	1200	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMxo1200E-4BN256C	1200	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMxo1200E-5BN256C	1200	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMxo1200E-3FTN256C	1200	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMxo1200E-4FTN256C	1200	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMxo1200E-5FTN256C	1200	1.2V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3TN100C	2280	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMxo2280E-4TN100C	2280	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMxo2280E-5TN100C	2280	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMxo2280E-3TN144C	2280	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMxo2280E-4TN144C	2280	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMxo2280E-5TN144C	2280	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMxo2280E-3MN132C	2280	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMxo2280E-4MN132C	2280	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMxo2280E-5MN132C	2280	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMxo2280E-3BN256C	2280	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMxo2280E-4BN256C	2280	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMxo2280E-5BN256C	2280	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMxo2280E-3FTN256C	2280	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMxo2280E-4FTN256C	2280	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMxo2280E-5FTN256C	2280	1.2V	211	-5	Lead-Free ftBGA	256	COM
LCMxo2280E-3FTN324C	2280	1.2V	271	-3	Lead-Free ftBGA	324	COM
LCMxo2280E-4FTN324C	2280	1.2V	271	-4	Lead-Free ftBGA	324	COM
LCMxo2280E-5FTN324C	2280	1.2V	271	-5	Lead-Free ftBGA	324	COM



MachXO Family Data Sheet

Revision History

June 2013

Data Sheet DS1002

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
		DC and Switching Characteristics	Security section updated.
			Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timingupdated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
		Pinout Information	JTAG Port Timing Specification updated (rev. A 0.16).
			SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	Logic Signal Connection section has been updated to include all devices/packages.
			Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/ LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

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